PD - 94266

International
IOR Rectifier

SMPS MOSFET

IRLR3714
IRLU3714

HEXFET® Power MOSFET

Applications

- High Frequency Isolated DC-DC Converters with Synchronous Rectification for Telecom and Industrial Use
- High Frequency Buck Converters for Computer Processor Power

V_{DSS}	$R_{DS(on)}$ max	I_D
20V	20mΩ	36A

D-Pak IRLR3714 | I-Pak IRLU3714

Benefits

- Ultra-Low Gate Impedance
- Very Low $R_{DS(on)}$ at 4.5V V_{GS}
- Fully Characterized Avalanche Voltage and Current

Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D @ T_C = 25°C	Continuous Drain Current, V_{GS} @ 10V	36 ⑤	A
I_D @ T_C = 70°C	Continuous Drain Current, V_{GS} @ 10V	31	
I_{DM}	Pulsed Drain Current①	140	
P_D @T_C = 25°C	Maximum Power Dissipation③	47	W
P_D @T_C = 70°C	Maximum Power Dissipation③	33	W
	Linear Derating Factor	0.31	W/°C
T_J , T_{STG}	Junction and Storage Temperature Range	-55 to + 175	°C

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	3.2	°C/W
$R_{\theta JA}$	Junction-to-Ambient	—	50	
$R_{\theta JA}$	Junction-to-Ambient (PCB mount)④	—	110	

Notes ① through ⑤ are on page 10

Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	20	—	—	V	V_{GS} = 0V, I_D = 250µA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.022	—	V/°C	Reference to 25°C, I_D = 1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	15	20	mΩ	V_{GS} = 10V, I_D = 18A ③
		—	21	28		V_{GS} = 4.5V, I_D = 14A ③
$V_{GS(th)}$	Gate Threshold Voltage	1.0	—	3.0	V	V_{DS} = V_{GS}, I_D = 250µA
I_{DSS}	Drain-to-Source Leakage Current	—	—	20	µA	V_{DS} = 16V, V_{GS} = 0V
		—	—	100		V_{DS} = 16V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Forward Leakage	—	—	200	nA	V_{GS} = 16V
	Gate-to-Source Reverse Leakage	—	—	-200		V_{GS} = -16V

Dynamic @ T_J = 25°C (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
g_{fs}	Forward Transconductance	17	—	—	S	V_{DS} = 10V, I_D = 14A
Q_g	Total Gate Charge	—	6.5	9.7	nC	I_D = 14A
Q_{gs}	Gate-to-Source Charge	—	1.8	—		V_{DS} = 10V
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	2.9	—		V_{GS} = 4.5V
Q_{oss}	Output Gate Charge	—	7.1	—		V_{GS} = 0V, V_{DS} = 10V
$t_{d(on)}$	Turn-On Delay Time	—	8.7	—	ns	V_{DD} = 10V
t_r	Rise Time	—	78	—		I_D = 14A
$t_{d(off)}$	Turn-Off Delay Time	—	10	—		R_G = 1.8Ω
t_f	Fall Time	—	4.5	—		V_{GS} = 4.5V ③
C_{iss}	Input Capacitance	—	670	—	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	—	470	—		V_{DS} = 10V
C_{rss}	Reverse Transfer Capacitance	—	68	—		f = 1.0MHz

Avalanche Characteristics

Symbol	Parameter	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy②	—	72	mJ
I_{AR}	Avalanche Current①	—	14	A

Diode Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	36⑤	—	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	140	—		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	T_J = 25°C, I_S = 18A, V_{GS} = 0V ③
		—	0.88	—		T_J = 125°C, I_S = 18A, V_{GS} = 0V ③
t_{rr}	Reverse Recovery Time	—	35	53	ns	T_J = 25°C, I_F = 18A, V_R=10V
Q_{rr}	Reverse Recovery Charge	—	34	51	nC	di/dt = 100A/µs ③
t_{rr}	Reverse Recovery Time	—	35	53	ns	T_J = 125°C, I_F = 18A, V_R=10V
Q_{rr}	Reverse Recovery Charge	—	35	53	nC	di/dt = 100A/µs ③

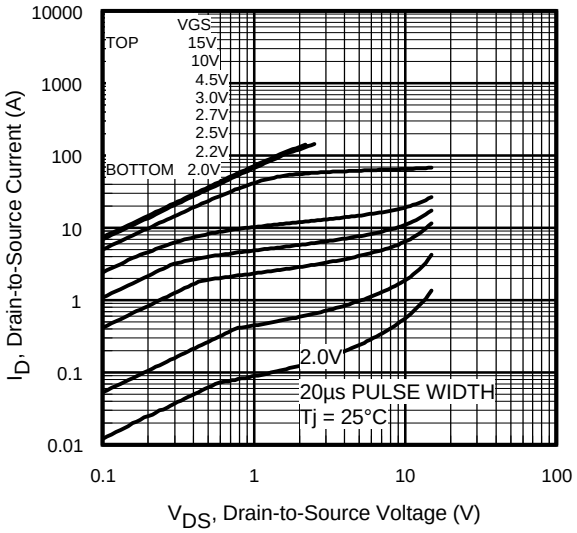


Fig 1. Typical Output Characteristics

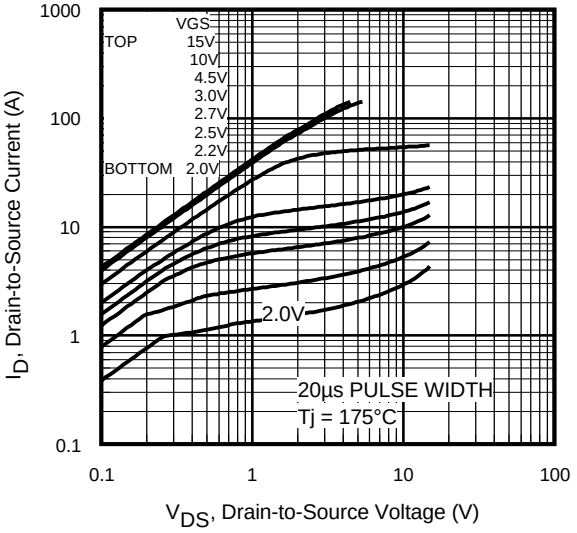


Fig 2. Typical Output Characteristics

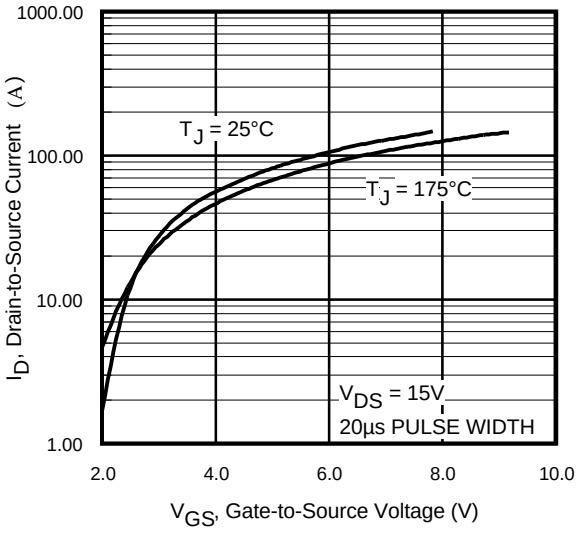


Fig 3. Typical Transfer Characteristics

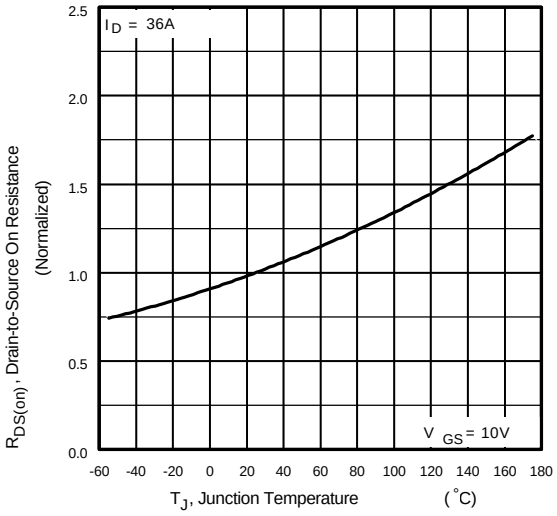


Fig 4. Normalized On-Resistance Vs. Temperature

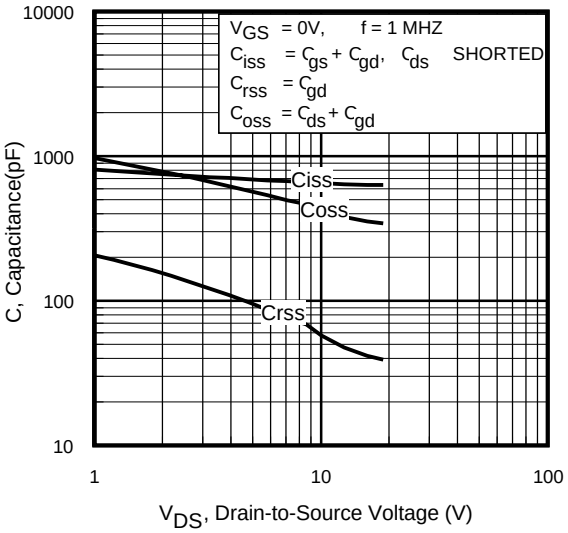


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

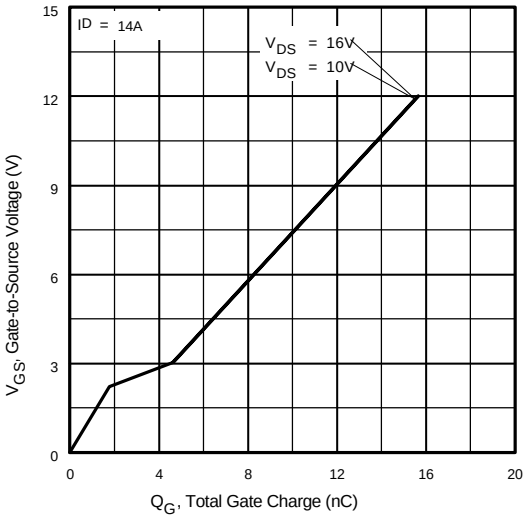


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

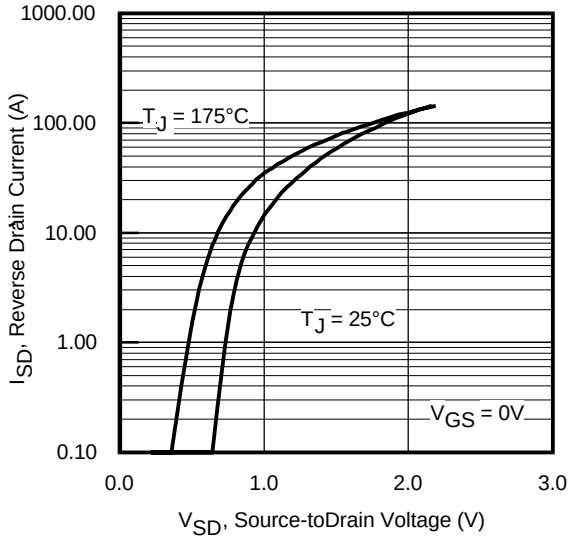


Fig 7. Typical Source-Drain Diode Forward Voltage

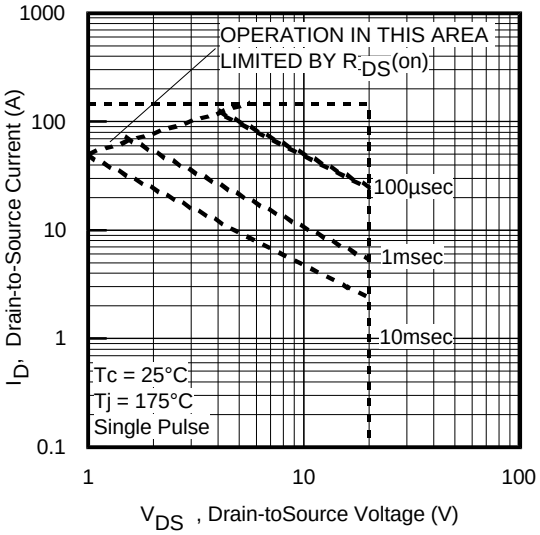


Fig 8. Maximum Safe Operating Area

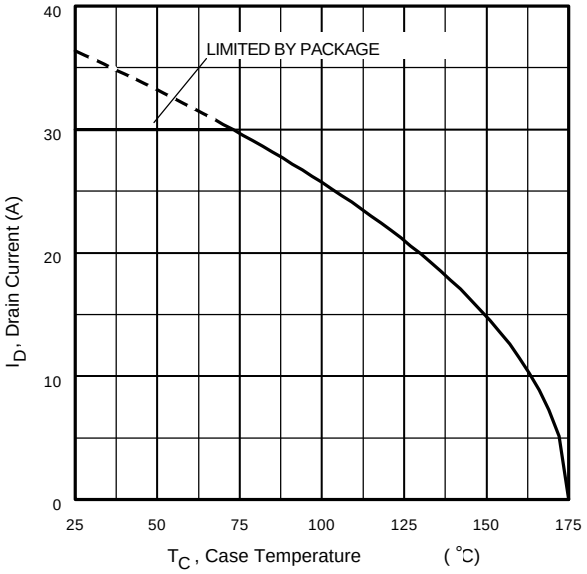


Fig 9. Maximum Drain Current Vs. Case Temperature

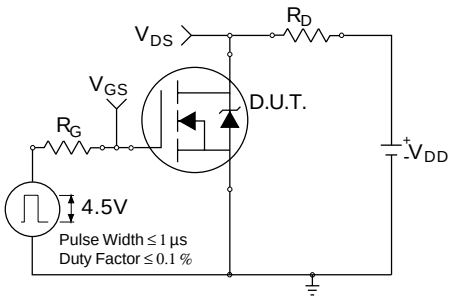


Fig 10a. Switching Time Test Circuit

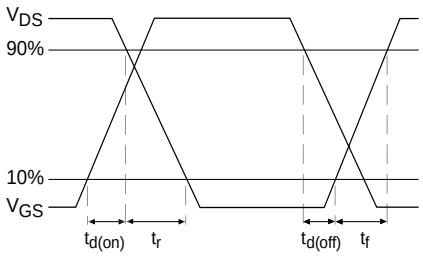


Fig 10b. Switching Time Waveforms

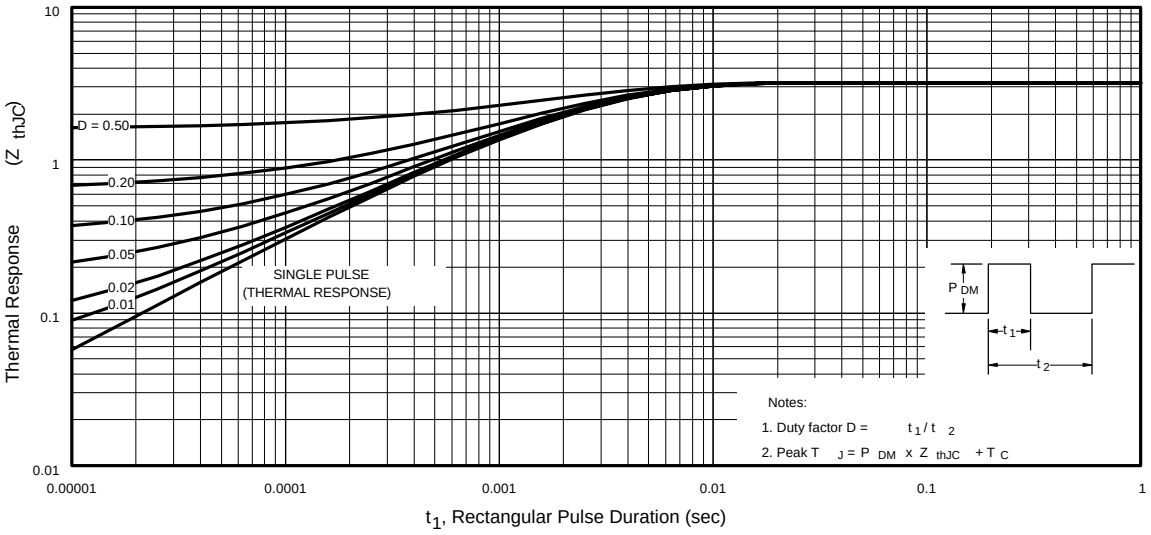


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

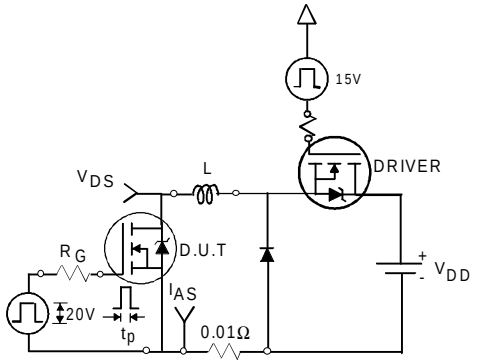


Fig 12a. Unclamped Inductive Test Circuit

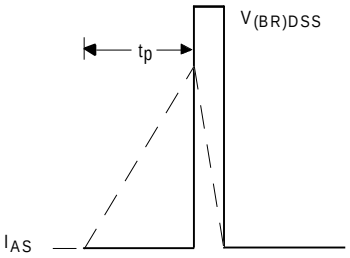


Fig 12b. Unclamped Inductive Waveforms

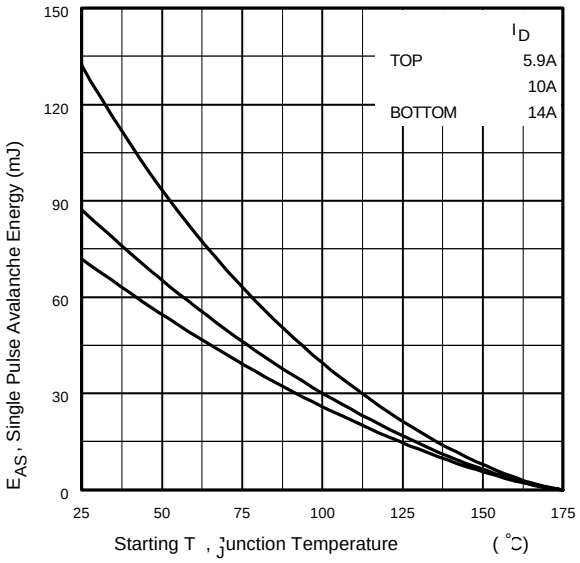


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

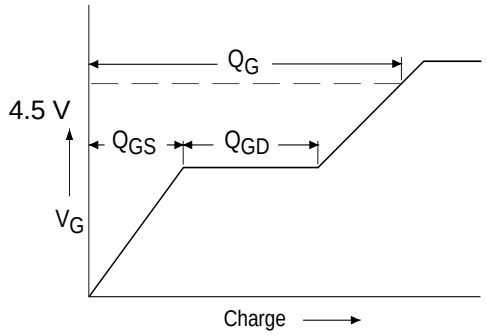


Fig 13a. Basic Gate Charge Waveform

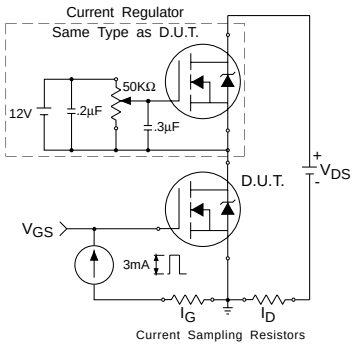
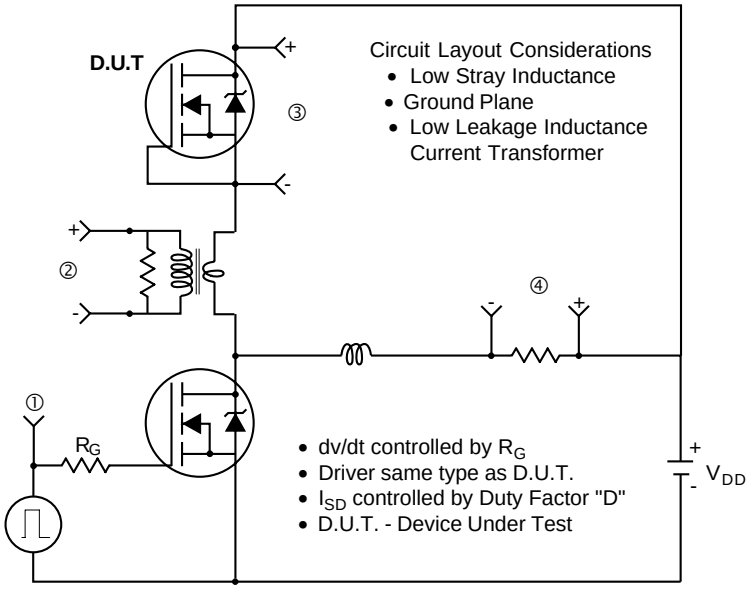
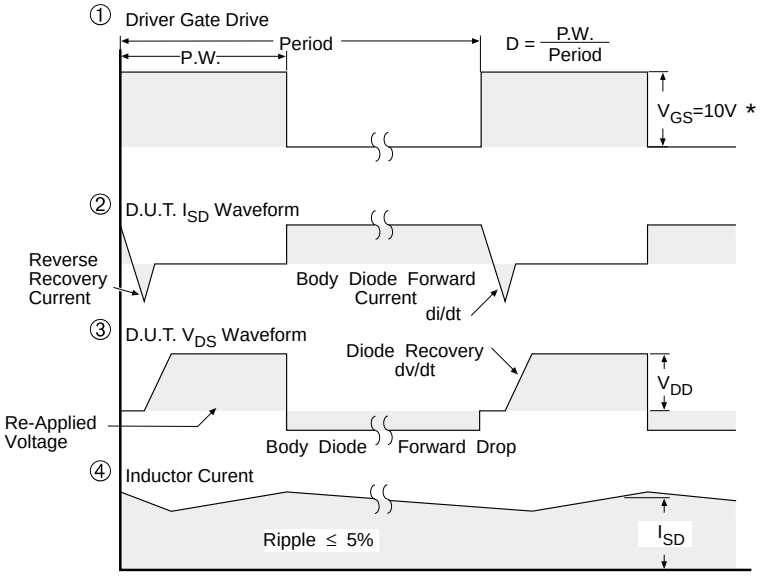


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



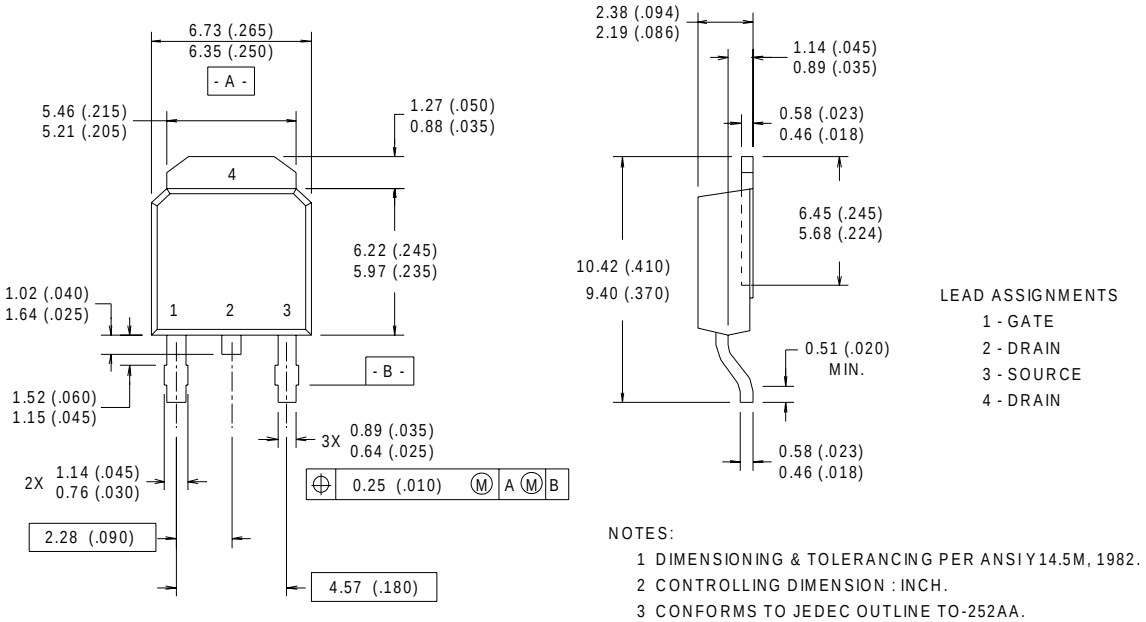


* V_{GS} = 5V for Logic Level Devices

Fig 14. For N-Channel HEXFET® Power MOSFETs

D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)

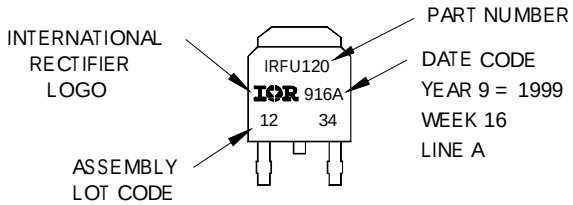


LEAD ASSIGNMENTS
1 - GATE
2 - DRAIN
3 - SOURCE
4 - DRAIN

NOTES:
1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
2 CONTROLLING DIMENSION : INCH.
3 CONFORMS TO JEDEC OUTLINE TO-252AA.
4 DIMENSIONS SHOWN ARE BEFORE SOLDER DIP, SOLDER DIP MAX. +0.16 (.006).

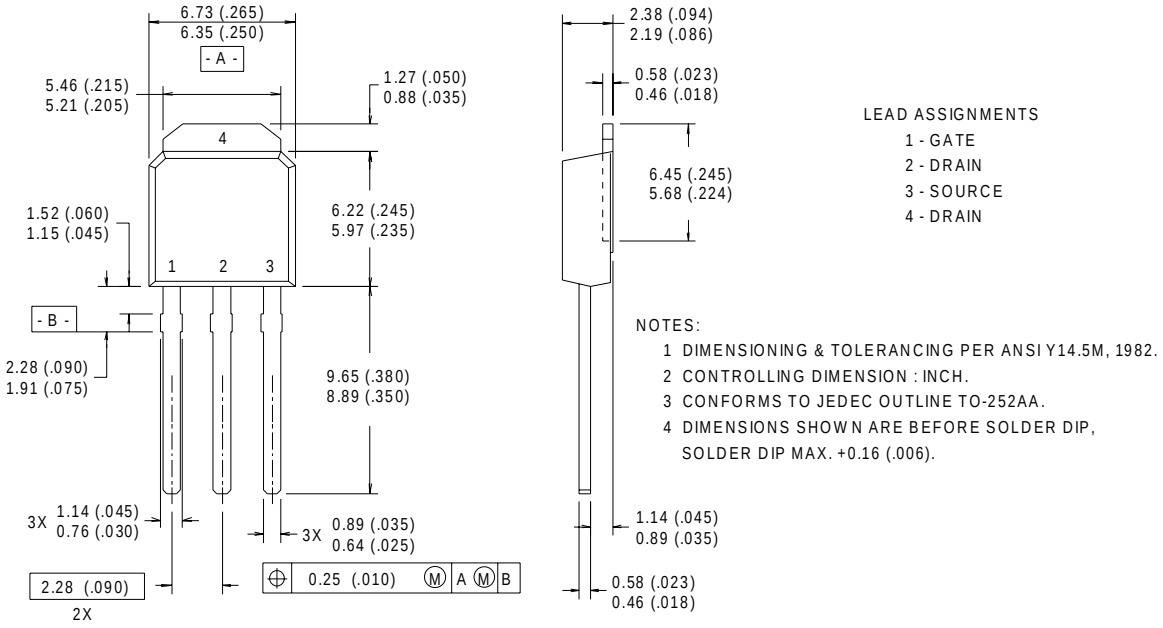
D-Pak (TO-252AA) Part Marking Information

EXAMPLE: THIS IS AN IRFR120
WITH ASSEMBLY
LOT CODE 1234
ASSEMBLED ON WW 16, 1999
IN THE ASSEMBLY LINE "A"



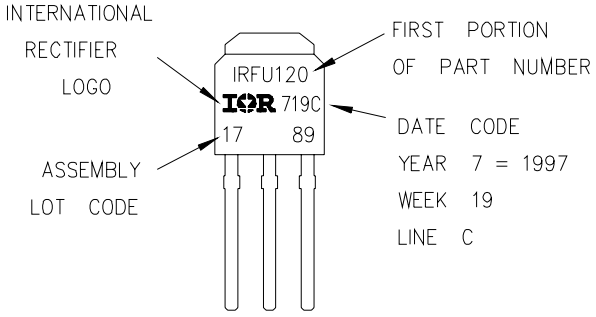
I-Pak (TO-251AA) Package Outline

Dimensions are shown in millimeters (inches)



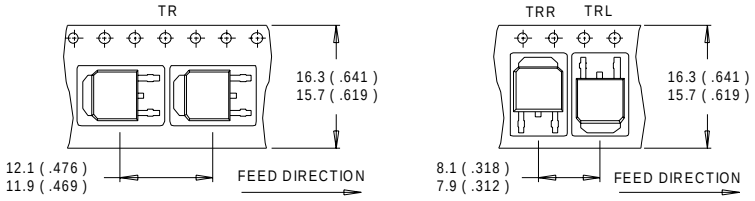
I-Pak (TO-251AA) Part Marking Information

EXAMPLE: THIS IS AN IRFU120
LOT CODE 1789
ASSEMBLED ON WW 19, 1997
IN THE ASSEMBLY LINE "C"

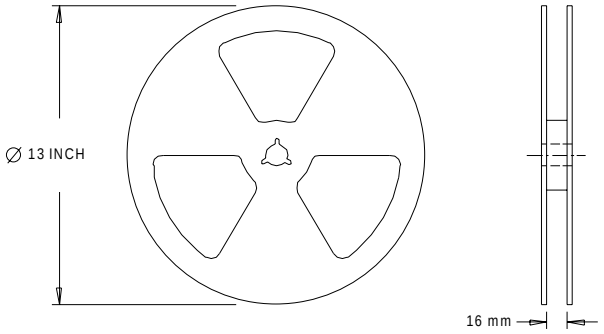


D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :
1. OUTLINE CONFORMS TO EIA-481.

Notes:

① Repetitive rating; pulse width limited by max. junction temperature.

② Starting T_J = 25°C, L = 0.69 mH R_G = 25Ω, I_{AS} = 14A.

③ Pulse width ≤ 400µs; duty cycle ≤ 2%.

④ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.

⑤ Calculated continuous current based on maximum allowable junction temperature; Package limitation current is 30A

Data and specifications subject to change without notice.
These products have been designed and qualified for the Industrial market.
Qualification Standards can be found on IR's Web site.

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Note: For the most current drawings please refer to the IR website at:
http://www.irf.com/package/